

**EH2525ETTS-48.000M**
[Click part number to visit Part Number Details page](#)
**REGULATORY COMPLIANCE** (Data Sheet downloaded on Apr 24, 2017)
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**ITEM DESCRIPTION**

Quartz Crystal Clock Oscillators XO (SPXO) HCMOS/TTL (CMOS) 5.0Vdc 4 Pad 5.0mm x 7.0mm Ceramic Surface Mount (SMD) 48.000MHz  $\pm 25$ ppm -40°C to +85°C

**ELECTRICAL SPECIFICATIONS**

|                                       |                                                                                                                                                                                                                                        |
|---------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Nominal Frequency                     | 48.000MHz                                                                                                                                                                                                                              |
| Frequency Tolerance/Stability         | $\pm 25$ ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration) |
| Aging at 25°C                         | $\pm 5$ ppm/year Maximum                                                                                                                                                                                                               |
| Operating Temperature Range           | -40°C to +85°C                                                                                                                                                                                                                         |
| Supply Voltage                        | 5.0Vdc $\pm 10\%$                                                                                                                                                                                                                      |
| Input Current                         | 50mA Maximum (No Load)                                                                                                                                                                                                                 |
| Output Voltage Logic High (Voh)       | 2.4Vdc Minimum with TTL Load, Vdd-0.4Vdc Minimum with HCMOS Load (IOH= -16mA)                                                                                                                                                          |
| Output Voltage Logic Low (Vol)        | 0.4Vdc Maximum with TTL Load, 0.5Vdc Maximum with HCMOS Load (IOL= +16mA)                                                                                                                                                              |
| Rise/Fall Time                        | 6nSec Maximum (Measured at 0.8Vdc to 2.0Vdc with TTL Load; Measured at 20% to 80% of waveform with HCMOS Load)                                                                                                                         |
| Duty Cycle                            | 50 $\pm 5$ (%) (Measured at 50% of waveform with TTL Load or with HCMOS Load)                                                                                                                                                          |
| Load Drive Capability                 | 10TTL Load or 50pF HCMOS Load Maximum                                                                                                                                                                                                  |
| Output Logic Type                     | CMOS                                                                                                                                                                                                                                   |
| Pin 1 Connection                      | Tri-State (High Impedance)                                                                                                                                                                                                             |
| Tri-State Input Voltage (Vih and Vil) | +2.2Vdc Minimum to enable output, +0.8Vdc Maximum to disable output (High Impedance), No Connect to enable output.                                                                                                                     |
| Absolute Clock Jitter                 | $\pm 250$ pSec Maximum, $\pm 100$ pSec Typical                                                                                                                                                                                         |
| One Sigma Clock Period Jitter         | $\pm 50$ pSec Maximum, $\pm 30$ pSec Typical                                                                                                                                                                                           |
| Start Up Time                         | 10mSec Maximum                                                                                                                                                                                                                         |
| Storage Temperature Range             | -55°C to +125°C                                                                                                                                                                                                                        |

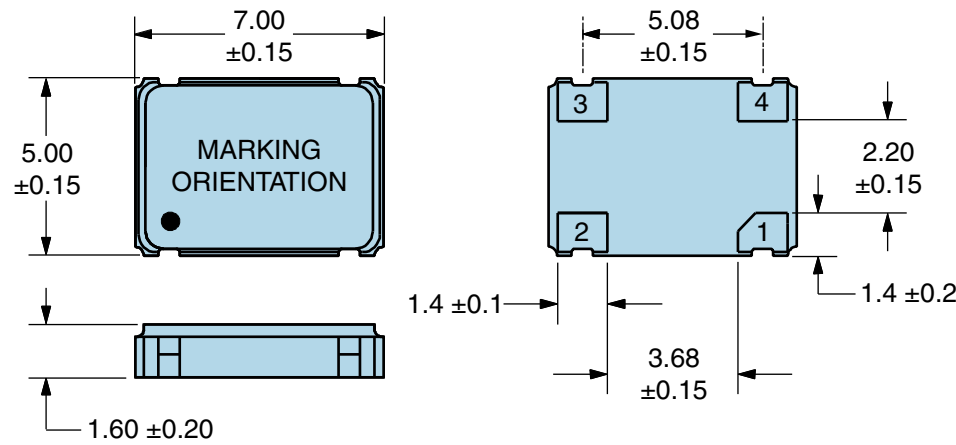
**ENVIRONMENTAL & MECHANICAL SPECIFICATIONS**

|                              |                                               |
|------------------------------|-----------------------------------------------|
| ESD Susceptibility           | MIL-STD-883, Method 3015, Class 1, HBM: 1500V |
| Fine Leak Test               | MIL-STD-883, Method 1014, Condition A         |
| Flammability                 | UL94-V0                                       |
| Gross Leak Test              | MIL-STD-883, Method 1014, Condition C         |
| Mechanical Shock             | MIL-STD-883, Method 2002, Condition B         |
| Moisture Resistance          | MIL-STD-883, Method 1004                      |
| Moisture Sensitivity         | J-STD-020, MSL 1                              |
| Resistance to Soldering Heat | MIL-STD-202, Method 210, Condition K          |
| Resistance to Solvents       | MIL-STD-202, Method 215                       |
| Solderability                | MIL-STD-883, Method 2003                      |
| Temperature Cycling          | MIL-STD-883, Method 1010, Condition B         |
| Vibration                    | MIL-STD-883, Method 2007, Condition A         |

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MECHANICAL DIMENSIONS (all dimensions in millimeters)



| PIN | CONNECTION     |
|-----|----------------|
| 1   | Tri-State      |
| 2   | Ground         |
| 3   | Output         |
| 4   | Supply Voltage |

| LINE | MARKING                                               |
|------|-------------------------------------------------------|
| 1    | ECLIPTEK                                              |
| 2    | 48.000M                                               |
| 3    | XXXXXX<br>XXXXXX=Ecliptek<br>Manufacturing Identifier |

Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

OUTPUT WAVEFORM & TIMING DIAGRAM



## Test Circuit for TTL Output

| Output Load<br>Drive Capability | R <sub>L</sub> Value<br>(Ohms) | C <sub>L</sub> Value<br>(pF) |
|---------------------------------|--------------------------------|------------------------------|
| 10TTL                           | 390                            | 15                           |
| 5TTL                            | 780                            | 15                           |
| 2TTL                            | 1100                           | 6                            |
| 10LSTTL                         | 2000                           | 15                           |
| 1TTL                            | 2200                           | 3                            |

Table 1:  $R_L$  Resistance Value and  $C_L$  Capacitance Value Vs. Output Load Drive Capability



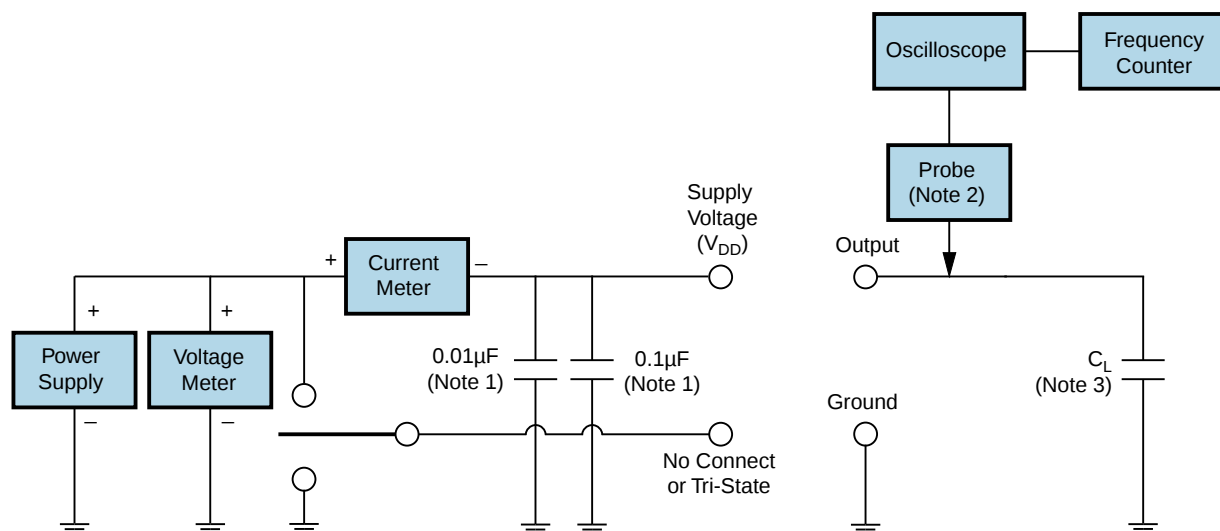
Note 1: An external 0.1μF low frequency tantalum bypass capacitor in parallel with a 0.01μF high frequency ceramic bypass capacitor close to the package ground and V<sub>DD</sub> pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance.

Note 4: Resistance value  $R_L$  is shown in Table 1. See applicable specification sheet for 'Load Drive Capability'.

Note 5: All diodes are MMBD7000, MMBD914, or equivalent.

**Test Circuit for CMOS Output**

Note 1: An external 0.1µF low frequency tantalum bypass capacitor in parallel with a 0.01µF high frequency ceramic bypass capacitor close to the package ground and  $V_{DD}$  pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance.

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Recommended Solder Reflow Methods



High Temperature Infrared/Convection

|                                     |                                                   |
|-------------------------------------|---------------------------------------------------|
| TS MAX to TL (Ramp-up Rate)         | 3°C/Second Maximum                                |
| Preheat                             |                                                   |
| - Temperature Minimum (TS MIN)      | 150°C                                             |
| - Temperature Typical (TS TYP)      | 175°C                                             |
| - Temperature Maximum (TS MAX)      | 200°C                                             |
| - Time (ts MIN)                     | 60 - 180 Seconds                                  |
| Ramp-up Rate (TL to TP)             | 3°C/Second Maximum                                |
| Time Maintained Above:              |                                                   |
| - Temperature (TL)                  | 217°C                                             |
| - Time (tL)                         | 60 - 150 Seconds                                  |
| Peak Temperature (TP)               | 260°C Maximum for 10 Seconds Maximum              |
| Target Peak Temperature (TP Target) | 250°C +0/-5°C                                     |
| Time within 5°C of actual peak (tP) | 20 - 40 Seconds                                   |
| Ramp-down Rate                      | 6°C/Second Maximum                                |
| Time 25°C to Peak Temperature (t)   | 8 Minutes Maximum                                 |
| Moisture Sensitivity Level          | Level 1                                           |
| Additional Notes                    | Temperatures shown are applied to body of device. |

**EH2525ETTS-48.000M**
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**Recommended Solder Reflow Methods****Low Temperature Infrared/Convection 240°C**

|                                            |                                                        |
|--------------------------------------------|--------------------------------------------------------|
| <b>TS MAX to TL (Ramp-up Rate)</b>         | 5°C/Second Maximum                                     |
| <b>Preheat</b>                             |                                                        |
| - Temperature Minimum (TS MIN)             | N/A                                                    |
| - Temperature Typical (TS TYP)             | 150°C                                                  |
| - Temperature Maximum (TS MAX)             | N/A                                                    |
| - Time (ts MIN)                            | 60 - 120 Seconds                                       |
| <b>Ramp-up Rate (TL to TP)</b>             | 5°C/Second Maximum                                     |
| <b>Time Maintained Above:</b>              |                                                        |
| - Temperature (TL)                         | 150°C                                                  |
| - Time (tL)                                | 200 Seconds Maximum                                    |
| <b>Peak Temperature (TP)</b>               | 240°C Maximum                                          |
| <b>Target Peak Temperature (TP Target)</b> | 240°C Maximum 2 Times / 230°C Maximum 1 Time           |
| <b>Time within 5°C of actual peak (tP)</b> | 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time |
| <b>Ramp-down Rate</b>                      | 5°C/Second Maximum                                     |
| <b>Time 25°C to Peak Temperature (t)</b>   | N/A                                                    |
| <b>Moisture Sensitivity Level</b>          | Level 1                                                |
| <b>Additional Notes</b>                    | Temperatures shown are applied to body of device.      |

**Low Temperature Manual Soldering**

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

**High Temperature Manual Soldering**

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)